metals

IMPACT FACTOR 2.6

CITESCORE 4.9

an Open Access Journal by MDPI

Research on Green and Environmentally Friendly Lead-Free Solder and Advanced Interconnect Technology in Electronic Packaging

Guest Editor:

Prof. Dr. Limin Ma
Faculty of Materials and Manufacturing, Beijing University of Technology, Beijing, China

Deadline for manuscript submissions:
closed (30 July 2024)

Message from the Guest Editor

Dear Colleagues,

In the process of connecting microelectronics, the industry not only needs to prohibit the doping of harmful elements from the source, but also ensure the reliability of the connection. This requires researchers to propose new strategies in terms of connection technology, materials and structural design. Since the end of the 1990s, many researchers have attempted to improve the reliability of tin-based solder and to regulate the properties of intermetallic compounds to weaken the brittle tendency of solder joints, whether they are from the source solder itself, the interface coating or external conditions. In addition, the reuse of solid waste resources of electronic products is also a new theme of green connection, and the design of electronic products should also consider the convenience of recycling. Methods of recovering valuable rare elements from electronic products is also an important issue.

mdpi.com/si/161066

Special Issue

metals

IMPACT FACTOR 2.6

CITESCORE 4.9

an Open Access Journal by MDPI

Editors-in-Chief

Prof. Dr. Hugo F. Lopez
Department of Materials Science and Engineering, College of Engineering & Applied Science, University of Wisconsin-Milwaukee, 3200 N. Cramer Street, Milwaukee, WI 53211, USA

Prof. Dr. Yong Zhang
Beijing Advanced Innovation Center of Materials Genome Engineering, State Key Laboratory for Advanced Metals and Materials, University of Science and Technology Beijing, 30 Xueyuan Road, Beijing 100083, China

Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.
High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.
Journal Rank: JCR - Q2 (*Metallurgy and Metallurgical Engineering*) / CiteScore - Q1 (Metals and Alloys)

Contact Us

Metals Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/metals
metals@mdpi.com
X @Metals_MDPI